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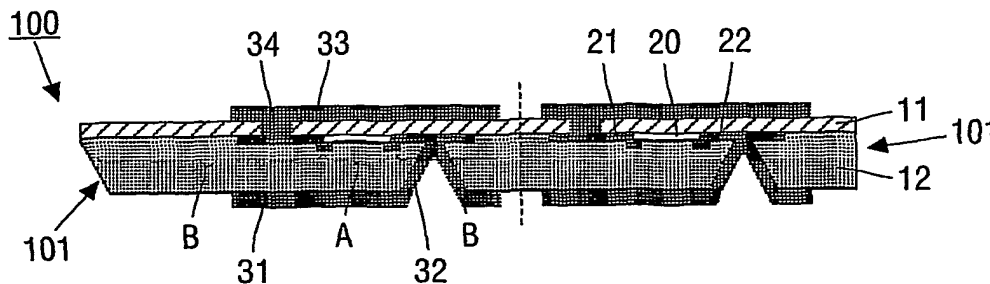
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(54) Title: SEMICONDUCTOR DEVICE, METHOD OF MANUFACTURING SAME, IDENTIFICATION LABEL AND INFORMATION CARRIER



(57) Abstract: The semiconductor device (100) comprises an integrated circuit (20) and a first and a second contact face (31,33). These are connected with vertical interconnects (32,34) to the integrated circuit (20). This integrated circuit (20) is present in a semiconductor layer of a substrate. This substrate is absent in a non-active area (B). This leads to the fact that on the side faces (101) of the device (100) neither conductive material nor parts of the semiconductor substrate are exposed. On lamination of the device between two metallized foils into an identification label, the risk of short-circuitry due to undesired contact at the side face (101) of the device (100), is prevented thereby.